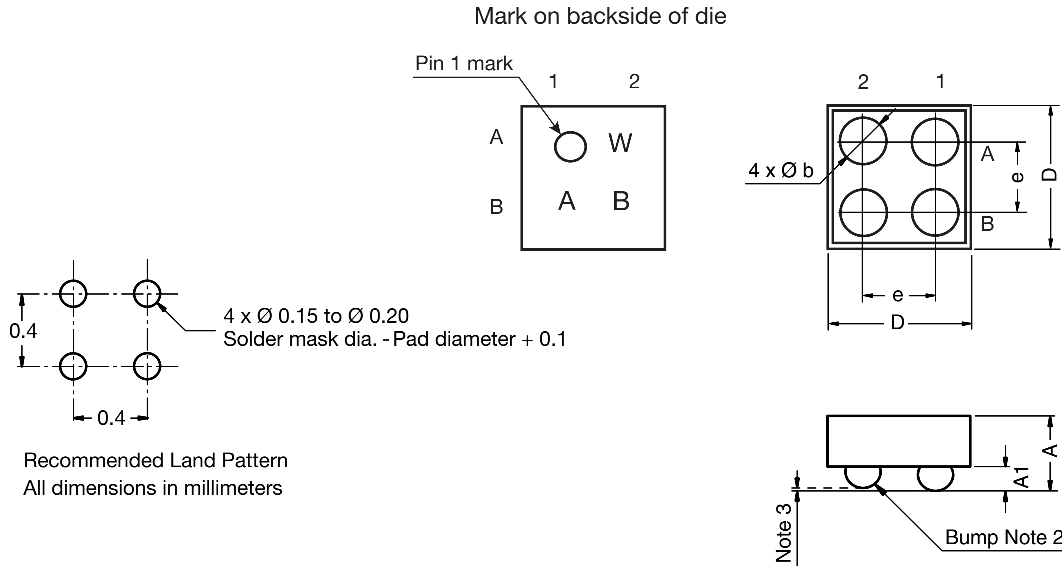
WCSP4: 4 Bumps

(2 x 2, 0.4 mm pitch, 208 µm bump height, 0.8 mm x 0.8 mm die size)



DWG-No: 6004

Notes

(1) Laser mark on the backside surface of die

(2) Bumps are SAC396

(3) 0.05 max. coplanarity

DIM.	MILLIMETERS [a]			INCHES		
	MIN.	**NOM.**	**MAX.**	**MIN.**	**NOM.**	**MAX.**
A	0.515	0.530	0.545	0.0203	0.0209	0.0215
A1		0.208			0.0082	
b	0.250	0.260	0.270	0.0098	0.0102	0.0106
e		0.400			0.0157	
D	0.720	0.760	0.800	0.0283	0.0299	0.0315

Note

a. Use millimeters as the primary measurement

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